



Specification of Automotive MLCC

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

A. Samsung Part Number

- Samsung P/N : CL10C181JB81PND
- Description : CAP, 180 pF, 50V, ±5%, C0G, 0603
- AEC-Q 200 Specified

		CL ①	<u>10</u> ②	<u>C</u> 3	<u>181</u> ④	<mark>ل</mark> 5	<u>B</u> 6	<mark>8</mark> ⑦	<u>1</u> ®	<u>P</u> 9	<u>N</u> 10	<u>₽</u> 11		
1	Series	ies Samsung Multi-layer Ceramic Capacitor												
2	Size	0603 (inch co	ode)		L:	1.6	6 ± 0.1	mm			W:		0.8 ± 0.1	mm
3	Dielectric	C0G				8	Inner	electr	ode		I	Ni		
4	Capacitance	180 pF					Term	inatior	า		(Cu		
5	Capacitance	±5 %					Platin	g			:	Sn 1	00%	(Pb Free)
	tolerance					9	Produ	uct				Auto	omotive	
6	Rated Voltage	50 V				10	Grade	e code	•		:	Star	ndard	
\bigcirc	Thickness	0.8 ± 0.1	mm			1	Packa	aging				Card	dboard Typ	e, 13"reel(10,000ea)

B. Reliability Test and Judgement condition

	Performance	Test condition					
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150°C					
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion					
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger						
	Q : 1000 min						
	IR : More than 10,000№ or 500№×μF						
	Whichever is Smaller						
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles					
	Capacitance Change :	Measurement at 24±2hrs after test conclusion					
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	1 cycle condition :					
	Q : 1000 min	-55+0/-3℃(15±3min) -> Room Temp(1min.)					
	IR : More than 10,000№ or 500№×μF	-> 125+3/-0℃(15±3min) -> Room Temp(1min.)					
	Whichever is Smaller						
Destructive Physical	No Defects or abnormalities	Per EIA 469					
Analysis							
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle					
	Capacitance Change :	Heat (25~65 $^\circ C$) and humidity (80~98%), Unpowered					
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	measurement at 24±2hrs after test conclusion					
	Q : 350 min						
	IR : More than 10,000№ or 500№×μF						
	Whichever is Smaller						
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 °C/85%RH, Rated Voltate and 1.3~1.5V,					
	Capacitance Change :	Add 100kohm resistor					
	within ±2.5% or ±0.25 ${}_{\text{p}}\text{F}$ whichever is larger	Measurement at 24±2hrs after test conclusion					
	Q : 200 min	The charge/discharge current is less than 50mA.					
	IR : More than 500MΩ or 25MΩ×μF						
	Whichever is Smaller						
High Temperature Appearance : No abnormal exterior appeara		1000hrs @ TA=125℃, 200% Rated Voltage,					
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion					
	within $\pm 3.0\%$ or ± 0.3 pF whichever is larger	The charge/discharge current is less than 50mA.					
	Q : 350 min						
	IR : More than 10,000 MΩ or 500 MΩ× μ F						
	Whichever is Smaller						

	Performance	Test condition						
External Visual	No abnormal exterior appearance	Visual inspection						
Physical Dimensions	Within the specified dimensions	Using The calipers						
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along						
	Capacitance Change :	3 mutually perpendicular axes of the test specimen (18 shocks)						
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	Peakvalue Duration Wave Velocity						
	Q, IR : initial spec.	1,500G 0.5ms Half sine 4.7m/sec.						
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,						
	Capacitance Change :	Use 8"x5" PCB 0.031" Thick 7 secure points on one long side						
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	and 2 secure points at corners of opposite sides. Parts mounted						
	Q, IR : initial spec.	within 2" from any secure point. Test from 10~2000 ${\rm Hz}.$						
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5 ℃, 10±1sec.						
Solder Heat	Capacitance Change :							
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger							
	Q, IR : initial spec.							
Thermal Shock	Appearance : No abnormal exterior appearance	-55°C/+125°C.						
	Capacitance Change :	Note: Number of cycles required-300,						
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Maximum transfer time-20 sec, Dwell time-15min. Air-Air						
	Q, IR : initial spec.							
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002						
	Capacitance Change :							
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger							
	Q, IR : initial spec.							
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245 \pm 5 °C						
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at $245\pm5^{\circ}$						
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C						
Fleetricel		solder : a solution ethanol and rosin						
Electrical Characterization	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25° C,						
Characterization	Q: 1000 max.	1₩±10%, 0.5~5Vrms						
	IR(25 °C) : More than 100,000№ or 1,000№×μF	I.R. should be measured with a DC voltage not exceeding						
	IR(125℃) : More than10,000ll or 100ll ×µF Whichever is Smaller	Rated Voltage @25°C, @125°C for 60~120 sec.						
	Dielectric Strength	Dielectric Strength : 250% of the rated voltage for 1~5 seconds						
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit (3mm) for 5 seconds						
Doard Flex	Capacitance Change :	Dending to the inflit (Jilling) for 5 seconds						
	within $\pm 5.0\%$ or $\pm 0.5 \text{ pF}$ whichever is larger							
Terminal	Appearance : No abnormal exterior appearance	10N, for 60±1 sec.						
Strength(SMD)	Capacitance Change :							
	within ±2.5% or ±0.25pF whichever is larger							
Beam Load	Destruction value should not be exceed	Beam speed						
	Chip Length < 2.5mm	0.5±0.05mm/sec						
	a) Chip Thickness > 0.5mm : 20N							
	b) Chip Thickness ≤ 0.5 mm : 2014							
Temperature	COG							
Characteristics	(From -55℃ to 125℃, Capacitance change should	be within ±30PPM/°C)						
	r , a participation of the second sec	- · /						

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max) Meet IPC/JEDEC J-STD-020 D Standard

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.